

AFE4900 Ultra-low Power, Integrated AFE for Wearable Optical, Electrical Bio-sensing with FIFO

1 Features

- Synchronized PPG, ECG signal acquisition at data rates up to 1 kHz
- ECG signal chain:
 - Standalone ECG acquisition up to 4 kHz
 - Input bias: 1-lead ECG with RLD bias
 - Programmable INA gain: 2.15 to 12.92
 - Input noise (1 Hz to 150 Hz): 2.5 μVrms at 1 kHz, 1.25 μVrms at 4-kHz data rate
 - AC, DC lead-off detect: 12.5-nA to 100-nA
 - IEC 60601 Test report available on request
- PPG receiver:
 - Supports three time-multiplexed PD inputs
 - 24-Bit representation of current from PD
 - DC offset subtraction DAC (Up to $\pm 126\text{-}\mu\text{A}$) at TIA input for each LED, ambient
 - Digital ambient subtraction at ADC output
 - Noise filtering with programmable bandwidth
 - Transimpedance gain: 10 k Ω to 2 M Ω
 - Dynamic range up to 100 dB
 - Receiver operates in PPG-only mode at approximately 1- $\mu\text{A}/\text{Hz}$ sampling rate
 - Power-down mode: approximately 0 μA
- PPG transmitter:
 - Four LEDs in common anode configuration
 - 8-Bit LED current up to 200 mA
 - Mode to fire two LEDs in parallel
 - Programmable LED on-time
 - Simultaneous support of three LEDs for SpO₂, or multiwavelength HRM
 - Average current of 30 μA adequate for a typical heart-rate monitoring scenario:
 - 20-mA Setting, 60- μs pulse duration, 25-Hz sampling rate
- Clocking using an external or internal clock
- FIFO with 128-sample depth for ECG and PPG
- I²C, SPI interfaces: selectable by pin
- 2.6-mm x 2.1-mm, 0.4-mm Pitch DSBGA package
- Supplies:
 - Rx: 1.8 V to 1.9 V (LDO bypass), 2.0 V to 3.6 V (LDO enabled)
 - Tx: 3 V to 5.25 V
 - IO: 1.7 V to Rx_SUP

2 Applications

- Synchronized PPG, ECG for blood pressure estimation
- HRM for wearables, hearables
- Heart-rate variability (HRV)
- Pulse oximetry (SpO₂) measurements

3 Description

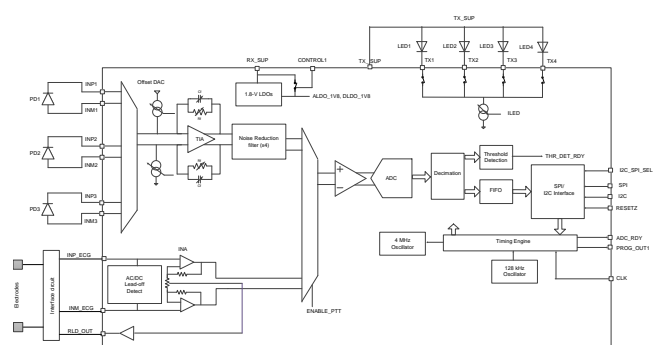
The AFE4900 device is an analog front-end (AFE) for synchronized electrocardiogram (ECG), photoplethysmogram (PPG) signal acquisition. The device can also be used for optical bio-sensing applications, such as heart-rate monitoring (HRM) and saturation of peripheral capillary oxygen (SpO₂). The PPG signal chain supports up to four switching light-emitting diodes (LEDs) and up to three photodiodes (PDs). The LEDs can be switched on using a fully integrated LED driver. The current from the photodiode is converted into voltage by the transimpedance amplifier (TIA) and digitized using an analog-to-digital converter (ADC). The ECG signal chain has an instrumentation amplifier (INA) with a programmable gain that interfaces to the same ADC. A right-leg drive (RLD) amplifier set can be used to the bias for the ECG input pins. AC and dc lead-off detect schemes are supported. The ADC codes from the PPG and ECG phases can be stored in a 128-sample first in, first out (FIFO) block and read out using either an I²C or a serial programming interface (SPI) interface.

Device Information⁽¹⁾

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|-------------|------------|-------------------|
| AFE4900 | DSBGA (30) | 2.60 mm x 2.10 mm |

(1) For all available packages, see the package option addendum at the end of the datasheet.

Simplified Block Diagram



4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Changes from Revision A (February 2019) to Revision B | Page |
|--|-------------|
| • Changed the values of <i>Programmable INA Gain</i> in <i>Features</i> section..... | 1 |
| • Changed the <i>Mechanical Packaging</i> images | 4 |

| Changes from Original (August 2017) to Revision A | Page |
|--|-------------|
| • Changed the values of <i>Programmable INA Gain</i> in <i>Features</i> section..... | 1 |
| • Added "IEC 60601 Test Report Available on Request" in <i>Features</i> section..... | 1 |

5 Device and Documentation Support

5.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

5.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

5.3 Trademarks

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5.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

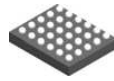
5.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

6 Mechanical, Packaging, and Orderable Information

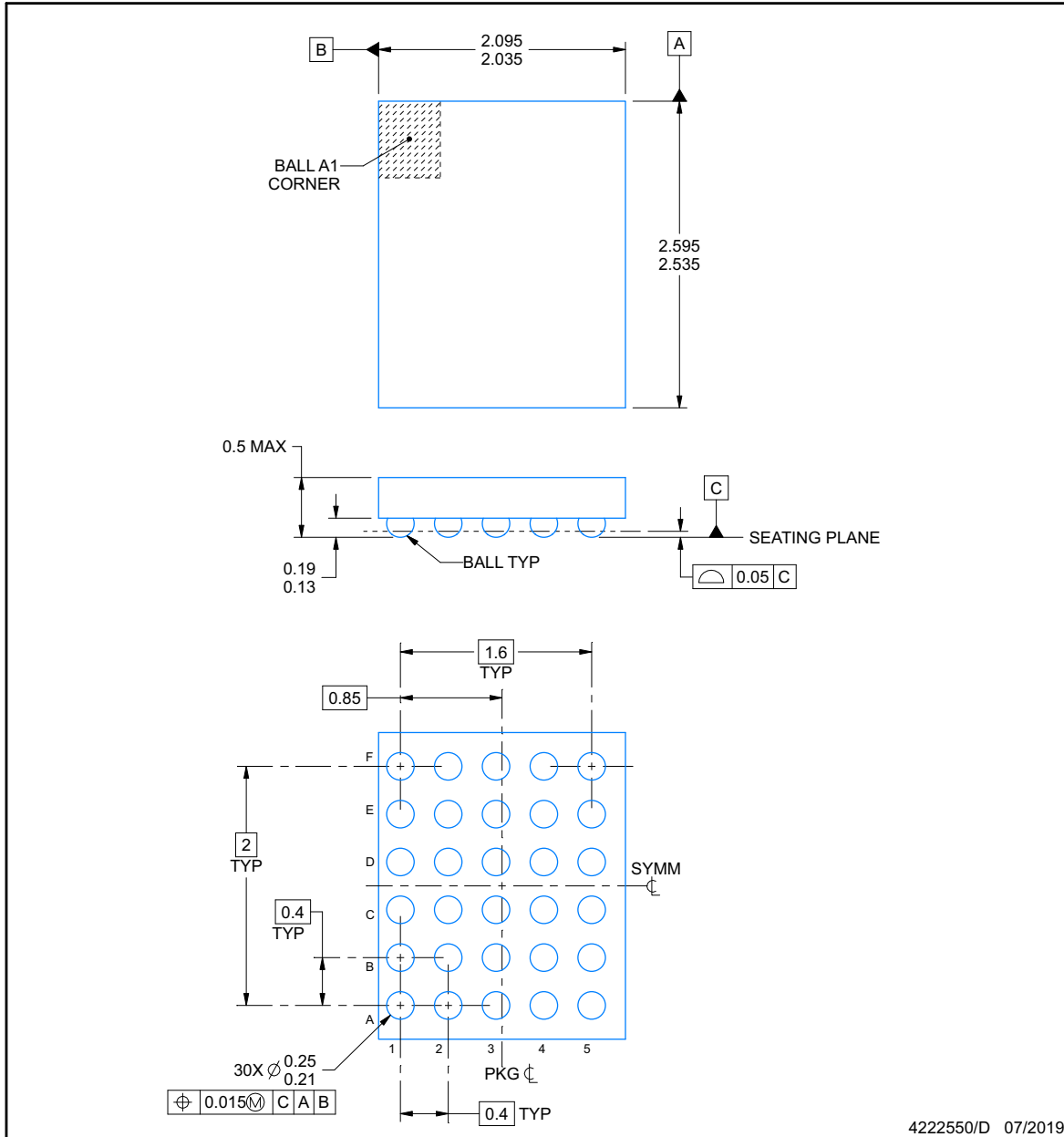
The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



YZ0030-C01

PACKAGE OUTLINE
DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



NOTES:

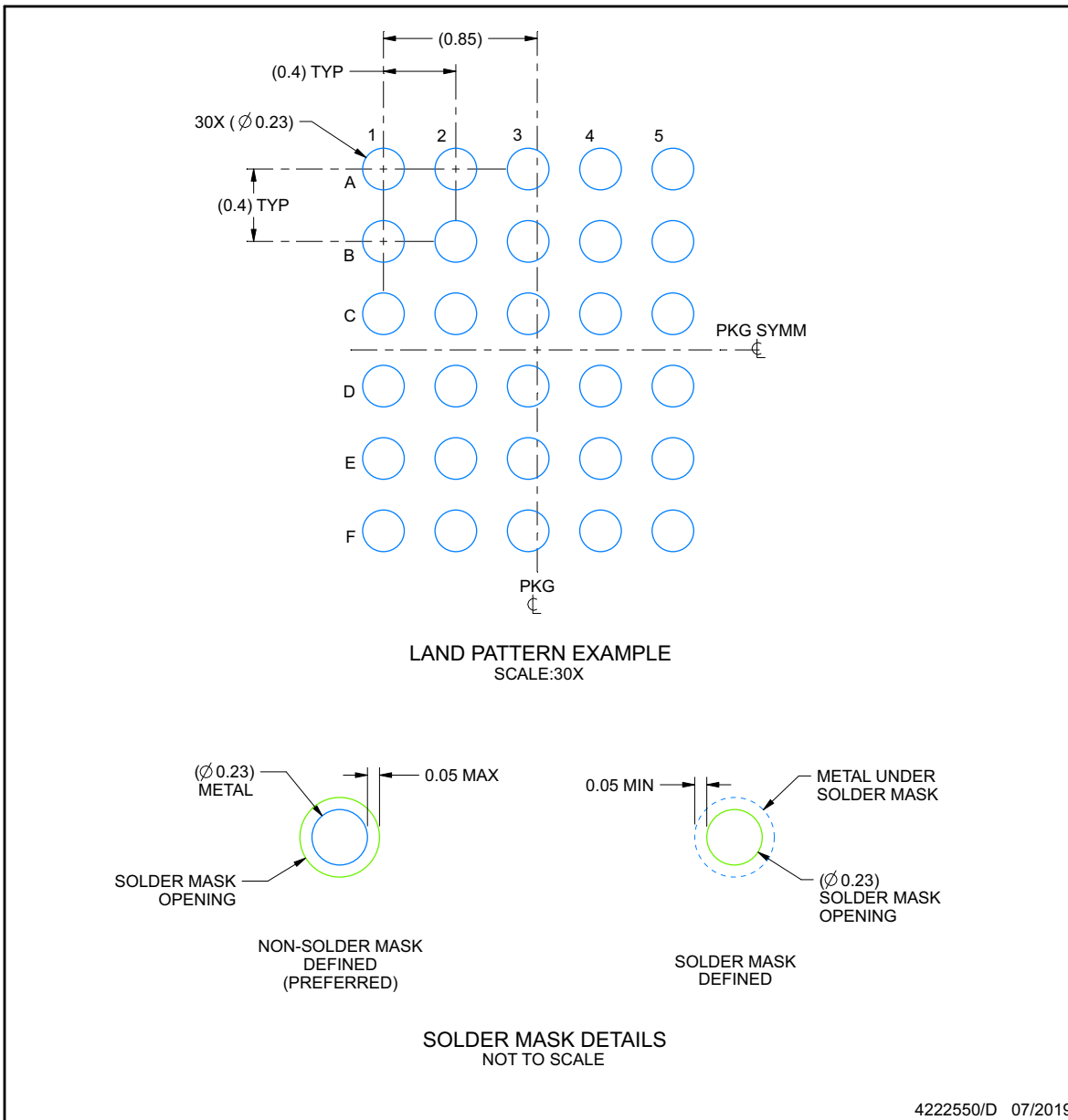
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

YZ0030-C01

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



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NOTES: (continued)

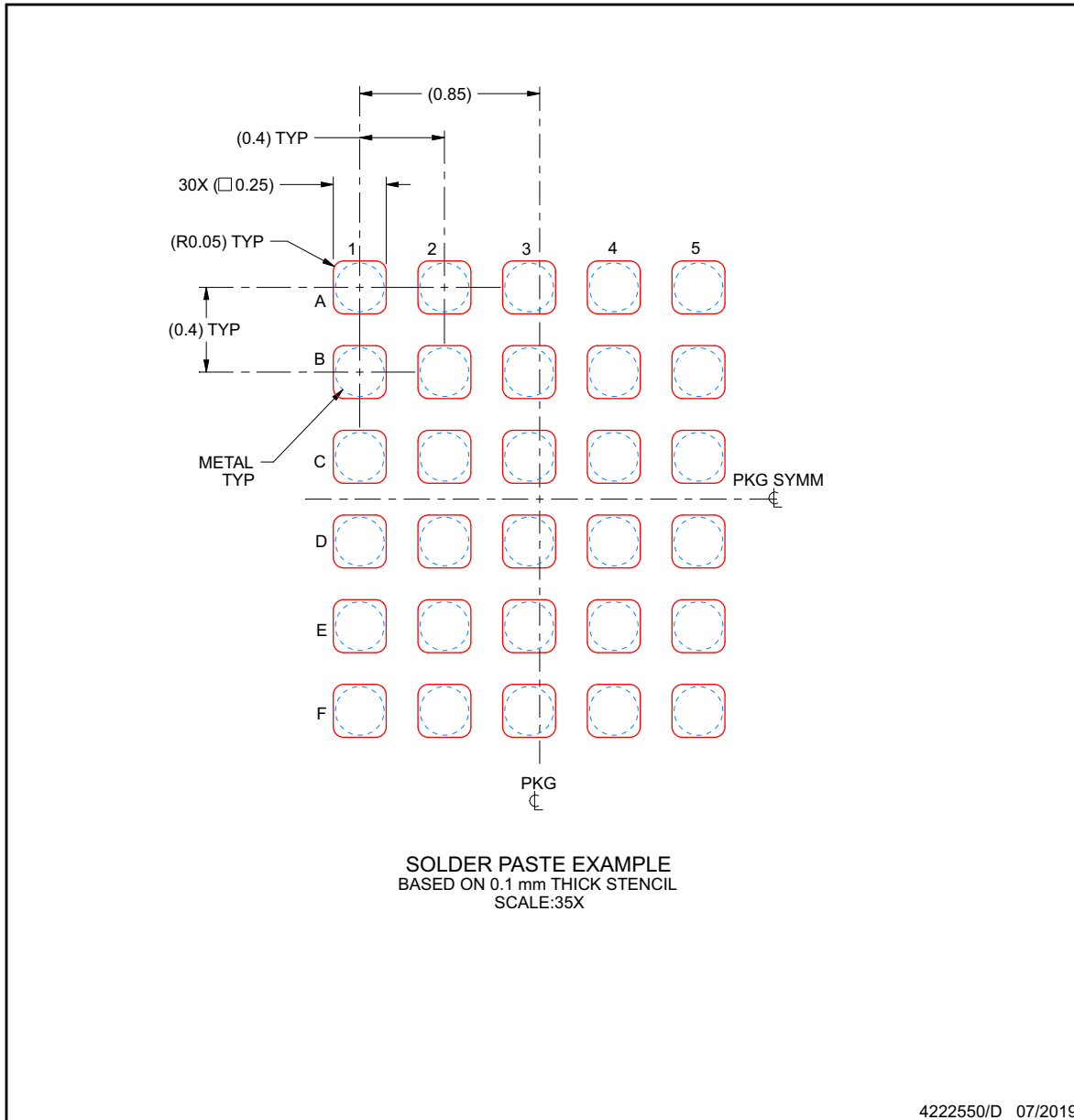
- 3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

YZ0030-C01

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



NOTES: (continued)

- 4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| AFE4900YZR | ACTIVE | DSBGA | YZ | 30 | 3000 | RoHS & Green | SAC396 | Level-1-260C-UNLIM | -20 to 70 | AFE4900 | Samples |
| AFE4900YZT | ACTIVE | DSBGA | YZ | 30 | 250 | RoHS & Green | SAC396 | Level-1-260C-UNLIM | -20 to 70 | AFE4900 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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